

In the United States Patent and Trademark Office

Serial Number:	10/760246		
Application. Filed:	January 21, 2004		
Applicant:	Kia Silverbrook; Norman Micheal Berry; Garry Raymond Jackson; Akira Nakazawa		
Application Title:	Printhead Assembly with Interconnected Printhead Modules		
Examiner/GAU:	Laura E Martin	2853	
	Dated	July 12, 2007	
	At:	Balmain, NSW	
	Docket No.	MPA10US	

REPLY

Commissioner for Patents
Washington, District of Columbia 20231

Dear Sir:

Applicant thanks Examiner for the detailed Office Action dated May 8, 2007. In response to the issues raised, the Applicant offers the following submissions.

35 U.S.C. §103 - Claims 1 and 5

Claims 1 and 5 stand rejected as obvious in light of US application 2002/0180834 to Silverbrook in view of US application 2002/0005878 to Moon. The Applicant disagrees as the citations do not disclose all the elements of claim 1, and hence claim 5.

Claim 1 is restricted to a printhead assembly that has two or more printhead modules. Each printhead module has a plurality of printhead ICs fixedly mounted to a support member. The '834 wide format printer design uses a plurality of ink reservoir moldings 74 as part of the printheads ink distribution arrangement 72. These moldings do not have a plurality of printhead ICs mounted to a support member. The '834 printhead modules 46 each have a single printhead IC 186 and they are removably mounted to the ink distribution system 72. Therefore, '834 does not disclose modules, as defined by claim 1, which are mounted in linear alignment and fluidly interconnected.

Moon teaches a single printhead IC 102 mounted to a larger support in the printhead. It is silent as to a printhead module with two or more printhead ICs each.

The cited references do not teach all the elements of claim 1 or claim 5. Accordingly, the citations do not support a §103 rejection of claims 1 or 5.